QUERY CONTR	OL FORM	RTIS USE ONLY			
Application No.	10/031,000	Prepared by	Lois Stone	Tracking Number	5920403
Examiner-GAU	Everhart - 2825	Date	4/30/04	Week Date	3/15/04
		No. of queries	1	Z FW	

JACKET					
a. Serial No.	f. Foreign Priority	k. Print Claim(s)	p. PTO-1449		
b. Applicant(s)	g. Disclaimer	I. Print Fig.	q. PTOL-85b		
c. Continuing Data	h. Microfiche Appendix	m. Searched Column	r. Abstract		
d. PCT	i. Title	n. PTO-270/328	s. Sheets/Figs		
e. Domestic Priority	j. Claims Allowed	o. PTO-892	t. Other		

SPECIFICATION	MESSAGE
a. Page Missing	Claim 28 (original claim 54) is listed on the
b. Text Continuity	Index of Claims but is canceled in the
c. Holes through Data	Index of Claims, but is canceled in the claims dated 12/11/2003 Please advise.
d. Other Missing Text	
e. Illegible Text	
f. Duplicate Text	
g. Brief Description	
h. Sequence Listing	
i. Appendix	
j. Amendments	
k. Other	
CLAIMS	
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b. Improper Dependency	Thanks you,
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the contact area increasing portion is formed of an extension portion-forming member brought in contact with the bump or the pattern forming surface located in a vicinity of the bump when the contact area is increased; and

the extension portion-forming member is pressurized against the bump or the pattern forming surface located in the vicinity of the bump.

51.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a cylindrical shape, a projecting portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

52.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a rugged portion at its tip, a rugged portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

53.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a cylindrical shape, a contact area increasing groove is formed in the vicinity of the bump by pressurizing the pattern forming surface in the vicinity of the bump by a pressurizing operation for performing pressurization with the extension portion-forming member, thus exposing the bump from the base material.

54.(Cancelled)